# Product End-of-Life Disassembly Instructions

**Product Category:** Personal Computers

**Marketing Name / Model**  
[List multiple models if applicable.]

HP Pavilion 24 All-in-One PC (Touch)

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**Purpose:** The document is intended for use by end-of-life recyclers or treatment facilities. It provides the basic instructions for the disassembly of HP products to remove components and materials requiring selective treatment, as defined by EU directive 2002/96/EC, Waste Electrical and Electronic Equipment (WEEE).

## 1.0 Items Requiring Selective Treatment

1.1 Items listed below are classified as requiring selective treatment.

1.2 Enter the quantity of items contained within the product which require selective treatment in the right column, as applicable.

<table>
<thead>
<tr>
<th>Item Description</th>
<th>Notes</th>
<th>Quantity of items included in product</th>
</tr>
</thead>
</table>
| Printed Circuit Boards (PCB) or Printed Circuit Assemblies (PCA) | With a surface greater than 10 sq cm  
Motherboard, RAM*, Touch control board | 4 |
| Batteries | All types including standard alkaline and lithium coin or button style batteries  
RTC battery | 1 |
| Mercury-containing components | For example, mercury in lamps, display backlights, scanner lamps, switches, batteries | |
| Liquid Crystal Displays (LCD) with a surface greater than 100 sq cm | Includes background illuminated displays with gas discharge lamps LCD | 1 |
| Cathode Ray Tubes (CRT) | | |
| Capacitors / condensers (Containing PCB/PCT) | | |
| Electrolytic Capacitors / Condensers measuring greater than 2.5 cm in diameter or height | | |
| External electrical cables and cords | EPS and power cord | 2 |
| Gas Discharge Lamps | | |
| Plastics containing Brominated Flame Retardants weighing > 25 grams (not including PCBs or PCAs already listed as a separate item above) | | |
| Components and parts containing toner and ink, including liquids, semi-liquids (gel/paste) and toner | Include the cartridges, print heads, tubes, vent chambers, and service stations. | |
| Components and waste containing asbestos | | |
| Components, parts and materials containing refractory ceramic fibers | | |

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PSG instructions for this template are available at [EL-MF877-01](EL-MF877-01)
Components, parts and materials containing radioactive substances

2.0 Tools Required

List the type and size of the tools that would typically be used to disassemble the product to a point where components and materials requiring selective treatment can be removed.

<table>
<thead>
<tr>
<th>Tool Description</th>
<th>Tool Size (if applicable)</th>
</tr>
</thead>
<tbody>
<tr>
<td>Description #1 Screwdriver</td>
<td>TORX T8</td>
</tr>
<tr>
<td>Description #2</td>
<td></td>
</tr>
<tr>
<td>Description #3</td>
<td></td>
</tr>
<tr>
<td>Description #4</td>
<td></td>
</tr>
<tr>
<td>Description #5</td>
<td></td>
</tr>
</tbody>
</table>

3.0 Product Disassembly Process

3.1 List the basic steps that should typically be followed to remove components and materials requiring selective treatment:

1. Removed Stand base
2. Removed Rear Cover
3. Removed Hinge
4. Removed Converter board & others
5. Removed ODD module
6. Removed HDD module
7. Remove MB Shielding
8. Removed Thermal module
9. Removed Fan module
10. Removed Base pan
11. Removed MB
12. Removed Speaker module
13. Removed Camera module
14. Removed LCD panel + Touch panel

3.2 Optional Graphic. If the disassembly process is complex, insert a graphic illustration below to identify the items contained in the product that require selective treatment (with descriptions and arrows identifying locations).

1. Removed Stand base

PSG instructions for this template are available at EL-MF877-01
2. Removed Rear Cover

3. Removed Hinge

4. Removed Converter board & others
5. Removed ODD module

6. Removed HDD module

7. Removed MB Shielding

8. Removed Thermal module
9. Removed Fan module

10. Removed Base pan

11. Removed MB

12. Removed Speaker module
13. Removed Camera module

14. Removed LCD panel + Touch panel